Small Signal MOSFET

60 V, 340 mA, Single, N-Channel, SC-70

Features

- ESD Protected
- Low R_{DS(on)}
- Small Footprint Surface Mount Package
- This is a Pb-Free Device

Applications

- · Low Side Load Switch
- Level Shift Circuits
- DC-DC Converter
- Portable Applications i.e. DSC, PDA, Cell Phone, etc.

MAXIMUM RATINGS $(T_J = 25^{\circ}C \text{ unless otherwise stated})$

Rating	Symbol	Value	Unit	
Drain-to-Source Voltage		V _{DSS}	60	V
Gate-to-Source Voltage		V _{GS}	±20	V
Drain Current (Note 1) Steady State t < 5 s	$T_A = 25^{\circ}C$ $T_A = 85^{\circ}C$ $T_A = 25^{\circ}C$ $T_A = 85^{\circ}C$	I _D	310 220 340 240	mA
Power Dissipation (Note 1) Steady State t < 5 s		P _D	280 330	mW
Pulsed Drain Current (t _p = 10 μ	I _{DM}	1.4	Α	
Operating Junction and Storag Temperature Range	T _J , T _{STG}	-55 to +150	°C	
Source Current (Body Diode)	I _S	250	mA	
Lead Temperature for Soldering (1/8" from case for 10 s)	T _L	260	°C	
Gate-Source ESD Rating (HBM, Method 3015)	ESD	900	V	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Junction-to-Ambient - Steady State (Note 1)	$R_{\theta JA}$	450	°C/W
Junction-to-Ambient - t ≤ 5 s (Note 1)	$R_{\theta JA}$	375	

 Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces)

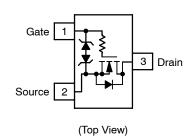


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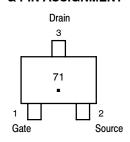
V _{(BR)DSS}	R _{DS(on)} MAX	I _D MAX (Note 1)
60 V	1.6 Ω @ 10 V	340 mA
	2.5 Ω @ 4.5 V	

Simplified Schematic



MARKING DIAGRAM & PIN ASSIGNMENT





71 = Device Code ■ Pb–Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
2N7002WT1G	SC-70 (Pb-Free)	3000/Tape & Reel

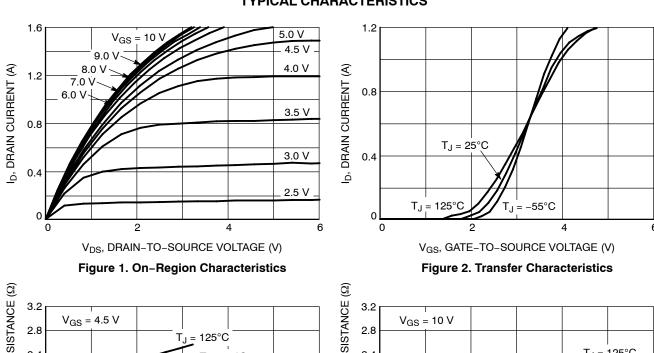
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

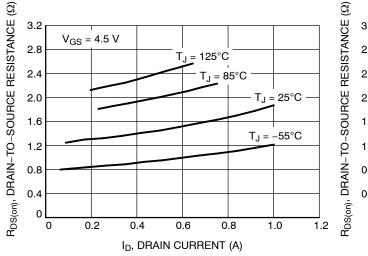
ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

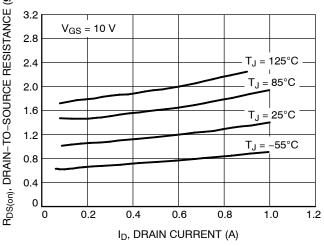
Parameter	Symbol	Test Co	ondition	Min	Тур	Max	Units
OFF CHARACTERISTICS	-	•		-	-		-
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J				71		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V,	T _J = 25°C			1	μΑ
		V _{DS} = 60 V	T _J = 125°C			500	μΑ
		V _{GS} = 0 V, V _{DS} = 50 V	T _J = 25°C			100	nA
Gate-to-Source Leakage Current	I _{GSS} V _{DS} = 0 V, V _{GS} = ±20 V		/ _{GS} = ±20 V			±10	μΑ
		V _{DS} = 0 V, \	/ _{GS} = ±10 V			450	nA
		V _{DS} = 0 V, V _{GS} = ±5.0 V				150	nA
ON CHARACTERISTICS (Note 2)	•	•			•		•
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}$	I _D = 250 μA	1.0		2.5	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J				4.0		mV/°C
Drain-to-Source On Resistance R _{DS(on)}		V _{GS} = 10 V, I _D = 500 mA			1.19	1.6	Ω
		V _{GS} = 4.5 V, I _D = 200 mA			1.33	2.5	
Forward Transconductance	9FS	V _{DS} = 5 V, I _D = 200 mA			80		S
CHARGES AND CAPACITANCES							
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 20 V			24.5		pF
Output Capacitance	C _{OSS}				4.2		
Reverse Transfer Capacitance	C _{RSS}				2.2		
Total Gate Charge	Q _{G(TOT)}				0.7		nC
Threshold Gate Charge	Q _{G(TH)}	V _{GS} = 4.5 V	, V _{DS} = 10 V;		0.1		
Gate-to-Source Charge	Q _{GS}		00 mA		0.3		
Gate-to-Drain Charge	Q_{GD}	1			0.1		1
SWITCHING CHARACTERISTICS, V _{GS}	= V (Note 3)			•			•
Turn-On Delay Time	t _{d(ON)}	V_{GS} = 10 V, V_{DD} = 25 V, I_{D} = 500 mA, R_{G} = 25 Ω			12.2		ns
Rise Time	t _r				9.0		
Turn-Off Delay Time	t _{d(OFF)}				55.8		1
Fall Time	t _f				29		1
DRAIN-SOURCE DIODE CHARACTER	ISTICS						
Forward Diode Voltage	V _{SD}	V _{GS} = 0 V,	T _J = 25°C		0.8	1.2	V
		I _S = 200 mA	T _J = 85°C		0.7]

Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%
 Switching characteristics are independent of operating junction temperatures

TYPICAL CHARACTERISTICS







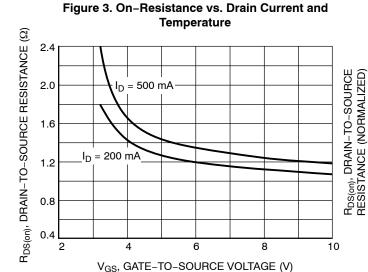


Figure 4. On–Resistance vs. Drain Current and Temperature



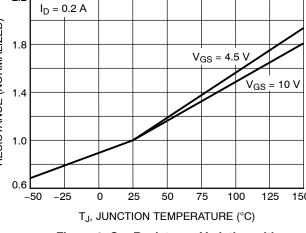


Figure 5. On-Resistance vs. Gate-to-Source Voltage

2.2

TYPICAL CHARACTERISTICS

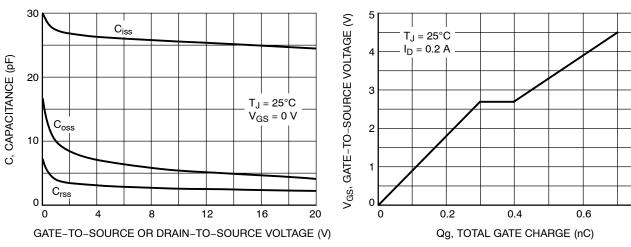


Figure 7. Capacitance Variation

Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

8.0

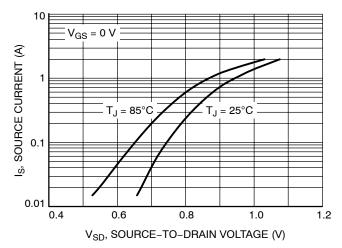
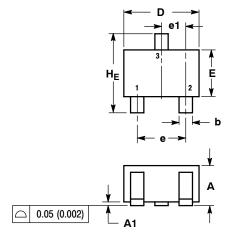


Figure 9. Diode Forward Voltage vs. Current

PACKAGE DIMENSIONS

SC-70 (SOT-323) CASE 419-04 ISSUE M





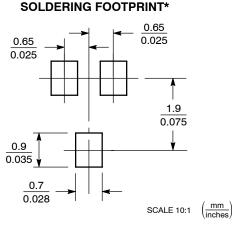
- NOTES:
- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	MOM	MAX	
Α	0.80	0.90	1.00	0.032	0.035	0.040	
A 1	0.00	0.05	0.10	0.000	0.002	0.004	
A2	0.7 REF			7 REF 0.028 REF			
b	0.30	0.35	0.40	0.012	0.014	0.016	
C	0.10	0.18	0.25	0.004	0.007	0.010	
D	1.80	2.10	2.20	0.071	0.083	0.087	
Е	1.15	1.24	1.35	0.045	0.049	0.053	
е	1.20	1.30	1.40	0.047	0.051	0.055	
e1	0.65 BSC			0.026 BSC			
L	0.425 REF			0.017 REF			
HE	2.00	2.10	2.40	0.079	0.083	0.095	

STYLE 8: PIN 1.

PIN 1. GATE
2. SOURCE

Δ2



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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